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|---|---|---|---|---|
| 1 | 106 | 716/$.ccls. and (jtag or tap or (boundary adj3 scan)) | USPAT | 2002/07/03 08:29 |
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| 3 | 79 | (716/$.ccls. and (jtag or tap or (boundary adj3 scan))) not (716/4.ccls. and (jtag or tap or (boundary adj3 scan))) | USPAT | 2002/07/03 08:30 |
| 4 | 78 | ((716/$.ccls. and (jtag or tap or (boundary adj3 scan))) not (716/4.ccls. and (jtag or tap or (boundary adj3 scan)))) and (multiple or plural or different or several) | USPAT | 2002/07/03 08:32 |
| 5 | 35 | ((716/$.ccls. and (jtag or tap or (boundary adj3 scan))) not (716/4.ccls. and (jtag or tap or (boundary adj3 scan)))) and ((multiple or plural or different or several) with device) | USPAT | 2002/07/03 10:31 |
| 6 | 5 | jtag and ((select$3 with (id or identification)) with code) | USPAT | 2002/07/03 11:02 |
| - | 998 | jtag | USPAT | 2002/05/01 15:04 |
| - | 502 | jtag and id$2 | USPAT | 2002/07/02 12:45 |
| - | 133 | jtag and id$2 and (reconfigur$7 or confirgur$7) | USPAT | 2002/05/01 15:06 |
| - | 123 | jtag and id$2 and (reconfigur$7 or confirgur$7) and software | USPAT | 2002/05/01 15:06 |
| - | 88 | jtag and (device with id$2) and (reconfigur$7 or confirgur$7) and software | USPAT | 2002/05/01 15:06 |
| - | 72190 | boundary adj2 scan or test adj access adj port or tap | USPAT | 2002/07/02 12:47 |
| - | 1870 | (boundary adj2 scan or test adj access adj port or tap) same (id or identification or code) | USPAT | 2002/07/02 12:48 |
| - | 1991 | (boundary adj2 scan or test adj access adj port or tap) same (id or identification or code) | USPAT | 2002/07/02 12:48 |
| - | 253 | ((boundary adj2 scan or test adj access adj port or tap) same (id or identification or code)) same voltage | USPAT | 2002/07/02 12:48 |
| - | 9 | (((boundary adj2 scan or test adj access adj port or tap) same (id or identification or code)) same voltage) same pin$2 | USPAT | 2002/07/02 15:25 |
| - | 1 | (tap with ((multiple or plural) with device with id)) | USPAT | 2002/07/02 15:27 |
| - | 2 | (tap same ((multiple or plural) with device with id)) | USPAT | 2002/07/02 15:28 |
| - | 2 | ((tap or jtag or (boundary adj3 scan)) same ((multiple or plural) with device with id)) | USPAT | 2002/07/02 15:29 |
| - | 215 | (plural or multiple) with id with code | USPAT | 2002/07/02 15:30 |
| - | 11 | ((plural or multiple) with id with code) and (jtag or tap) | USPAT | 2002/07/02 15:31 |
| - | 446 | 716/4.ccls. | USPAT | 2002/07/02 15:31 |
| - | 27 | 716/4.ccls. and (jtag or tap or (boundary adj3 scan)) | USPAT | 2002/07/03 08:28 |

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1 **An instruction fetch unit applicable to 32-bit and 16-bit instruction s together**
*Li Lin; Qi Jiayue*
ASIC, 2001. Proceedings. 4th International Conference on , 2001
Page(s): 869 -871

[Abstract]   [PDF Full-Text (282 KB)] **CNF**

---

2 **1.25 volt, low cost, embedded flash memory for low density applica**
*McPartland, R.J.; Singh, R.*
VLSI Circuits, 2000. Digest of Technical Papers. 2000 Symposium on , 2000
Page(s): 158 -161

[Abstract]   [PDF Full-Text (380 KB)] **CNF**

---

3 **A register-controlled symmetrical DLL for double-data-rate DRAM**
*Feng Lin; Miller, J.; Schoenfeld, A.; Ma, M.; Baker, R.J.*
Solid-State Circuits, IEEE Journal of , Volume: 34 Issue: 4 , April 1999
Page(s): 565 -568

[Abstract]   [PDF Full-Text (72 KB)] **JNL**

---

4 **Two types of sound tool f r editing speech signal: sound cutter and sound edit r**
*Sagisaka, T.; Munakata, T.*
Multimedia Computing and Systems, 1999. IEEE International Conference on ,
2 , 1999

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1 **A method for the measurement of chip to leadframe adhesion in LOC packages**
*Ahmad, S.S.; Tongbi Jiang; Moden, W.; Breen, C.; Reeder, J.*
Electronics Manufacturing Technology Symposium, 1996., Nineteenth IEEE/CP

Page(s): 402 -407

[Abstract]   [PDF Full-Text (584 KB)] **CNF**

---

2 **A model of temperature cycling performance in plastic encapsulated packages**
*Syndergaard, P.; Young, J.*
Integrated Reliability Workshop, 1994. Final Report., 1994 International , 199
Page(s): 37 -41

[Abstract]   [PDF Full-Text (364 KB)] **CNF**

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1 **High reliability, high density, low cost packaging systems for matrix for matrix BGA and CSP by vacuum printing encapsulation systems (V**
*Okuno, A.; Fujita, N.; Ishikawa, Y.*
Advanced Packaging, IEEE Transactions on [see also Components, Packaging Manufacturing Technology, Part B: Advanced Packaging, IEEE Transactions on
Volume: 22 Issue: 3 , Aug. 1999
Page(s): 391 -397

[Abstract]    [PDF Full-Text (1192 KB)] **JNL**

---

2 **High reliability, high density, low cost packaging systems for matrix CSP using VPES (vacuum printing encapsulation systems)**
*Okuno, A.*
Electronic Components & Technology Conference, 1998. 48th IEEE , 1998
Page(s): 109 -110

[Abstract]    [PDF Full-Text (256 KB)] **CNF**

---

3 **Recent progress in flexible moulding and reliability investigation  f BGA-packages using advanced interconnection technology**
*Ansorge, F.; Becker, K.-F.; Ehrlich, R.; Azdasht, G.; Bader, V.; Aschenbrenne Reichl, H.*
Polymeric Electronics Packaging, 1997. Proceedings., The First IEEE Internatio
Symposium on , 1997
Page(s): 14 -22

[Abstract]    [PDF Full-Text (1164 KB)] **CNF**

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26 **New thin plastic package crack mechanism, induced by hot IC die**
*Marks, M.R.*
Reliability Physics Symposium 1992. 30th Annual Proceedings., International
Page(s): 190 -197

[Abstract]   [PDF Full-Text (748 KB)] **CNF**

---

27 **Chip on tape qualification and reliability**
*Wang, T.-C.; Long, J.; Kwong, P.*
Multi-Chip Module Conference, 1992. MCMC-92, Proceedings 1992 IEEE , 199
Page(s): 72 -74

[Abstract]   [PDF Full-Text (172 KB)] **CNF**

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